

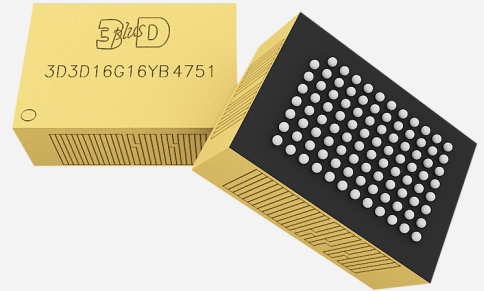
### UP-COMING PRODUCT

#### 16Gbit DDR3 (1Gbit x 16)

#### 3D3D16G16YB4751

3D PLUS is offering a new Space DDR3 solution organized with 4 chips of 4 Gbit and configured as x16-bit data.

Our DDR3 SDRAM memory is particularly well suited for missions requiring high-speed memory optimized for size, weight, reliability and power, with a long-term availability.



We are providing you one-step further solution compare to our previous DDR2 generation:

- Higher density (16 Gbit)
- Faster speed by proposing higher frequency (667 MHz)
- Lower power consumption (1.35 V compatible 1.5 V)

#### Excellent radiation reliability

- TID > 75 krad(Si)
- SEL Immune LET > 67Mev.cm<sup>2</sup>/mg

#### EM availability

- 3D3D16G16YB4751 (1 Git x16): Available
- 3D3D16G72WB2723 (256 Mbit x 72): Available
- 3D3D24G48YB3732 (512 Mbit x 48): Q3/19

#### CONTROLLER

The Radiation Intelligent Memory Controller (RIMC DDR3) is a fully configurable DDR3 SDRAM memory controller IP for data width from 8 bits to 144 bits. It includes Single Event Upset (SEU) mitigation and Single Event Functional Interrupt (SEFI) protection to be able to work in radiation environments.

Flyer will be available on the website in August.

### NEXT EXHIBITIONS



**SMALL SAT**  
LOGAN, UTAH, USA  
AUGUST 5-8  
Booth 45T



**NUCLEAR AND DECOMMISSIONING AND REMEDIATION EXPO**  
BIRMINGHAM, UK  
SEPT. 11-12



**RADECS**  
MONTPELLIER, FRANCE  
SEPT. 16-20  
Booth 29



**UK SPACE CONFERENCE**  
NEWPORT, UK  
SEPT. 24-26

### CONFERENCE ESPC

3D PLUS will be participating to the next **EUROPEAN SPACE POWER CONFERENCE (ESPC)** organized by the European Space Agency (30<sup>th</sup> Sept. - 4<sup>th</sup> Oct. in Juan-les-Pins, France).

**This year, three 3D PLUS' presentations (talks) are scheduled:**

- 1 3D PLUS Resonant POL Converter using GaN transistors
- 2 3D PLUS Intelligent Latch-up Current Limiter
- 3 Transformer optimization for 3D PLUS Universal RCN Front End converter



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### 3D PLUS ACQUIRES BERNIER COMPANY

We are proud to announce that BERNIER company, designer and manufacturer of connectors for harsh environments, now belongs to the HEICO Group. The company sells connectors for land and naval defense, security, military and civil aeronautics and industry fields.

We are very excited to work with their team, BERNIER's products is a great addition to our existing product portfolio and this will give us an access to new markets.

Click [here](#) to learn more about the acquisition

Click [here](#) to learn more about BERNIER company



### MEMORY MODULES ONBOARD OCO-3

3D PLUS has supplied **256 Mbit NOR Flash** (3DFO256M16VS4105) and **512 Mbit SDRAM** (3DSD512M16VS1605) to be embedded on-board the **OCO-3** (Orbiting Carbon Observatory-3) launched on May 4<sup>th</sup>.

OCO-3 is a space instrument developed by JPL. It will investigate important questions about the **distribution of carbon dioxide on Earth** as it relates to growing urban populations and changing patterns of fossil fuel combustion.

Click [here](#) to learn more about the mission



*Credit: NASA*

### eROSITA INSTRUMENT

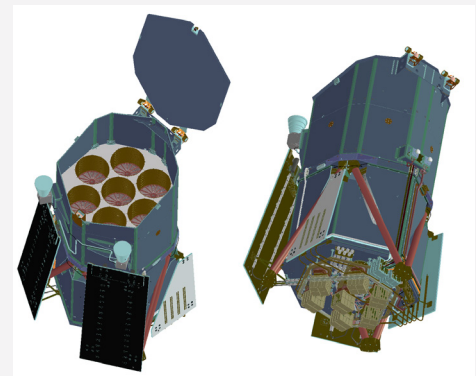
We provided several **128 Mbit NOR Flash** (3DFO128M16VS2282) and a RTIMS (Radiation Tolerant Intelligent Memory Stack) for the **eRosita** instrument on-board the Russian-German « Spectrum-Roentgen-Gamma » (SRG) space observatory.

It was launched on July 13th by Roscosmos.

eROSITA is an **X-Ray instrument** built by the **Max Planck Institute for Extraterrestrial Physics** (MPE), Germany. It will perform the first imaging all-sky survey in the medium energy X-ray range up to 10 keV with an unprecedented spectral and angular resolution.

Click [here](#) to learn more about the mission

[Youtube video](#)



*Credit: Max-Planck-Institut für extraterrestrische Physik*